

文件編號: E-B-AR01 版 次: A 頁 次:1 / 4

1.Style:

This specification describes "Rotary Switch" mainly used as signal switch of electric devices with the general requirements of mechanical and electrical characteristics.

1.1 Operating Temperature Range : -25 ~ +80°C 1.2 Storage Temperature Range : -40°C ~ +85°C

2. Current Range:

2.1 Non-Switching: 100mA, 50V DC 2.2 Switching: 25mA, 24V DC

3. Type of Actuation: Rotating

4. Test Sequence

	ITEM	DESCRIPTION	TEST CONDITIONS	REQUIREMENTS	
PERFORMANCE	1	Visual Examination	By visual examination check without any out pressure & testing.	There shall be no defects that affect the serviceability of the product.	
	2	Contact Resistance	 ①To be measured between the two terminals associated with each switch pole. ②Measurements shall be made with a 1kHz shall current contact resistance meter. 	100mΩ max. (initial)	
ELECTRIC	3	Insulation Resistance	250V DC, 1 minute ± 5 seconds.	100MΩ min.	
ELEC	4	Dielectric withstand- ing Voltage	250V AC (50Hz or 60 Hz) shall be applied between all the adjacent terminals and between the terminal and the frame for 1 minute.	There shall be no breakdown or flashover.	
	5	Capacitance	1 MHz ± 10 kHz	5 pF max.	
MECHANICAL PERFORMANCE	6	Operation Force	Applied in the direction of operation.	200gf·max (1.96N·max)	

文 件 編 號 : E-B-AR01 版 次 : A 頁 次 : 2 / 4

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	7	Stop Strength	A static load of 1 kgf vertical direction ope 15 seconds.	There shall be no sign of damage mechanically.	
	8		1.Soldering Tempera		
			P.C.BOARD TERMINAL RH \ RV	SMT TYPE TERMINAL RM	
			260 °ℂ±5°ℂ	See the Temperature	
빙			5±1sec	profile	As shown in item 2~6
N A			2.Duration of Solder Immersion:		
<u>Š</u>			5±1 sec. 3.Frequency of Soldering Process:		
PERFORMANCE			2 times max.		
出			(PCB is 1.6mm in		
MECHANICAL PI	9	Vibration	Shall be vibrated in a Method 201A of MIL 1)Frequency: 10-55-10 2)Direction: 3 vertical the direction of operat 3)Test Time: 2 hours e	As shown in item 2~6	
	10	Shock	Shall be shocked in ad Method 213B conditio 1)Acceleration: 50G. 2)Action Time: 11 ± 1 3)Testing Direction: 6: 4)Test cycle: 3 times	As shown in item 2~6	
	11	Solderability	1)Soldering Temperate 2)Flux: 5-10 seconds.	No anti-soldering and the coverage of dipping into solder must more than 75% was requested.	

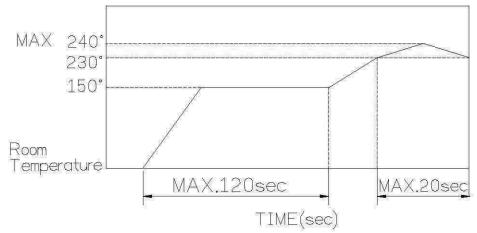
文 件 編 號 : E-B-AR01 版 次 : A 頁 次 : 3 / 4

25				
DUKABILI TV	12	Operation Life	1)25 mA, 24V DC resistive load 2)Rate of Operation: 15~20 cycles/ minute	1)As shown in item 3,4 2)Contact Resistance: 200mΩ max. 3)final-after test
WEATHER-PROOF	13	Resistance Low Temperature	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: -40°C±3°C 2)Time: 96 hours	As shown in item 2~6
	14	Resistance High Temperature	Following the test set forth below the Sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 85°C±2°C 2)Time: 96 hours	1)As shown in item 3~6 2)Contact Resistance: 200mΩ max.
WE	15	Resistance Humidity	Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before measurements are made: 1)Temperature: 40°C ±2°C 2)Relative Humidity:90~95% 3)Time: 96 hours	1) As shown in item 4,6 2)Contact Resistance: 200mΩ max. 3)Insulation Resistance: 10MΩ min.

文件編號: E-B-AR01 版 次: A 頁 次:4/4

5. SOLDERING CONDITIONS:

■ Condition for Soldering - RM Series



■The condition mentioned above is the temperature on the Cu foil of the PCB surface.

There are cases where board's temperature greatly differs from switch's surface temperature depending on board's material, size, thickness, etc. Care, therefore, should be used not to allow switch's surface temperature to exceed 240°C.

■Manual Soldering

Soldering Temperature	Max.350°C	
Continuous Soldering Time	Max. 3 seconds	

■ Precautions in Handling

Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch.

Please make sure that there is no flux rose over the surface of the PCB.

ITEM	DESC.	Q'TY	MATERIALS	TREATMENT	REMARK	
1.	COVER	1	HIGH – TEMP. THERMOPLASTIC NYLON 9T	MOLDED BLACK		
2.	SEALED RUBBER	1	SILICONE	(#	-	
3.	ACTUATOR	1	HIGH – TEMP. THERMOPLASTIC LCP	MOLDED WHITE		
4.	CONTACT	1	ALLOY COPPER	GOLD PLATED AT CONTACT AREA.		
5.	TERMINAL	1	BRASS	⊕GOLD PLATED AT CONTACT AREA, TIN/LEAD AT TERMINATION AREA②CONTACT AND TERMINAL PLATING:GOLD PLATING OVER NICKEL	ï	
6.	BASE	1	HIGH – TEMP. THERMOPLASTIC NYLON 9T	MOLDED BLACK	-	
REMARK: ① PROD. NO. : S□ □ □ □ □ □ □ □ □ □ □ □ □ □ □ □ □ □						